

In accordance with ESCC 9000

#	Process Flow Steps	Method / Condition	Sampling
1	Wafer Lot Acceptance	MIL-STD-883 TM5007	By diffusion Lot
2	Die Sawing and Select	Internal procedure and MIL-STD-883 TM2010 / A	100%
3	Die attach	Internal procedure	100%
4	Die shear or Stud pull	MIL-STD-883 TM2019 or TM2027	Monitoring
5	Wire bonding	Internal procedure	100%
6	Destructive Wire Bond pull	MIL-STD-883 TM2011	Monitoring
7	Wire Bond shear	Internal procedure / ASTM F 1269-06	Monitoring
8	Internal Visual Inspection	Internal procedure and MIL-STD-883 TM2010 A / ESCC 20400	100%
9	Customer / e2v inspector inspection	MIL-STD-883 TM2010 / A (Internal source)	By assay lot
10	Lid attach / Sealing	Internal procedure	100%
11	Stabilization	MIL-STD-883 TM1008	100%
12	Temperature Cycling	MIL-STD-883 TM1010 / C / 10 cycles	100%
13	PIND test	MIL-STD-883 TM2020 / A	100%
14	Marking & serialization	Internal procedure / per Device Specification	100%
15	Pre-Burn-in electrical	Per Device Specification / +25°C / +datalog	100%
16	Burn-In	MIL-STD-883 TM1015 / 240h / 125°C	100%
17	Post-Burn-In (Interim) Electrical	Per Device Specification / +25°C / +datalog	100%
18	Drift calculation	Per Device Specification (amb temp) / +datalog	100%
19	PDA	5% PDA (amb temp) / +datalog	By lot
20	Extreme temp. Electrical	Per Device Specification / +125°C / -55°C / +datalog	100%
21	Fine & Gross leaks test	MIL-STD-883, TM1014 / A / C	100%
22	Final Electrical (+Group A)	Per Device Specification / +25°C	100%
23	Physical dimension control	Per Device Specification	100%
24	External Visual	MIL-STD-883 TM2009	100%
25	Customer / e2v inspector inspection	MIL-STD-883 TM2009 / A (final source)	By lot
26	Packing	Internal procedure	100%
27	Certificate of Compliance	MIL-PRF-38535	By delivery

Lot Acceptance Test (LAT)	Method / Condition	Termination	Sampling
LAT1 - Environmental	ESCC 9000 - Chart F4a	No	All lots
LAT1 - Mechanical	ESCC 9000 - Chart F4a	No	All lots
LAT2 - Endurance	ESCC 9000 - Chart F4a	No	All lots
LAT3 - Capability	ESCC 9000 - Chart F4a	Yes	Per Assy lot
Group E – RHA	ESCC Basic Specification No. 22900	-	If required in PO

* Quality notes	Sampling
Screening for LGA / CCGA / CI-CGA packages	-
Flight Models delivered with CD-rom including :	By delivery
- Flight Model traceability / Final source inspection report	
- Internal source inspection report	
- SEM analysis (Die construction analysis)	
- Electrical measurements of delivered FM	
- LAT report	
- CoC	

Useful address / Link	
ESCIES	https://escies.org
Mil Specs and Drawings	www.landandmaritime.dla.mil
Contact Teledyne-e2v Marketing	semiconductors.MKT@Teledyne-e2v.com
Visit teledyne-e2v website	www.teledyne-e2v.com